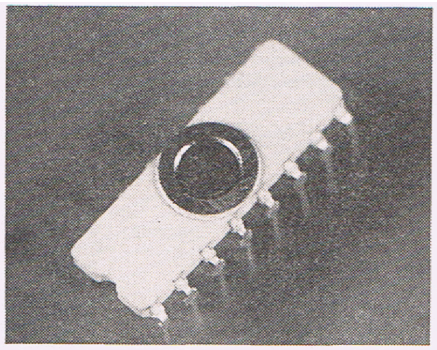
1970
Pin insertion type laminated ceramic package development
-Packaging-

Using the laminated ceramic technology introduced by RCA, a pin-insertion type DILC (Dual In Line Ceramic) 16-pin with a pin pitch of 100 mils (2.54 mm) and a row pitch of 300 mils was developed and mass-produced at the Musashi Plant of Hitachi, Ltd. in 1967. rice field.

The DILC16 pin has been adopted for ICs for electronic exchanges, which have begun to replace crossbar exchanges.

The following year, around 1970, 24-pin and 28-pin DILCs were developed and produced, and were applied to ICs for calculators, MSI, etc. The photo on the right side of the figure below shows a 2-chip 1 package in which 2 LSI elements are mounted in one package. After the elements were mounted, they were bent 90 degrees and then pin-inserted and soldered to a printed circuit board.

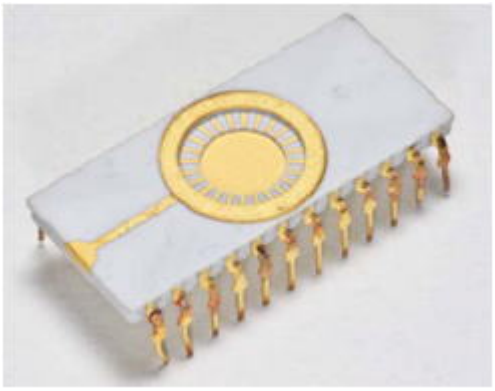
16-pin DILC (finished product)



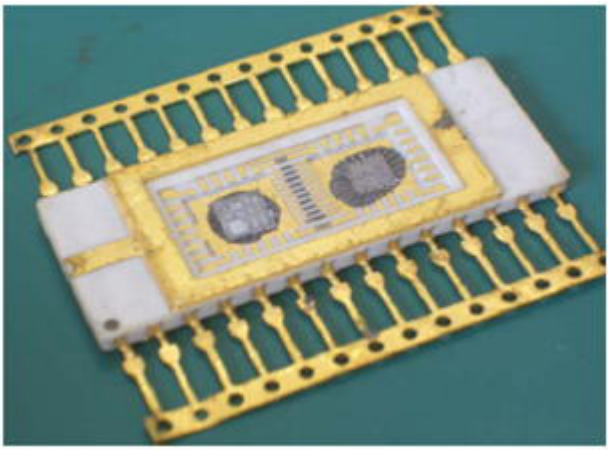
積層セラミックパッケージ（ＤＩＬＣ）

図2-14-7　ＲＣＡ社から技術導入したパッケージ例

24-pin DILC (before device assembly)



28-pin DILC (2-element LSI assembly completed before sealing)



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パッケージング年表に戻る . ↑前の詳細ページへ ↓次の詳細ページへ

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